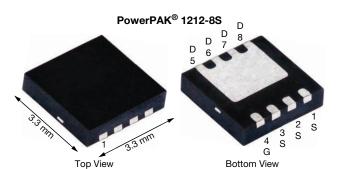




N-Channel 80 V (D-S) MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	80				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0072				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.0087				
Q _g typ. (nC)	31.5				
I _D (A)	63				
Configuration	Single				

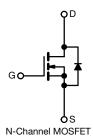
FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low R_{DS} Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} Q_{oss} FOM
- 100 % R_a and UIS tested
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Synchronous rectification
- Primary side switch
- DC/DC converter
- Solar micro inverter
- · Motor drive switch
- · Battery and load switch
- Industrial



ORDERING INFORMATION	
Package	PowerPAK 1212-8S
Lead (Pb)-free and halogen-free	SiSS32DN-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	80	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		63		
	T _C = 70 °C	1 .	50.3		
	T _A = 25 °C	I _D	17.4 ^{b, c}		
	T _A = 70 °C		13.9 ^{b, c}	Α	
Pulsed drain current (t = 100 μs)		I _{DM}	м 150		
October a second desired and a second	T _C = 25 °C		59.7		
Continuous source-drain diode current	T _A = 25 °C	I _S	4.5 ^{b, c}		
Single pulse avalanche current		I _{AS}	20		
Single pulse avalanche energy L = 0.1 mH		E _{AS}	20	mJ	
	T _C = 25 °C		65.7		
Maximum power dissipation	T _C = 70 °C		42	w	
	T _A = 25 °C	P _D	5 b, c		
	T _A = 70 °C		3.2 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	0.0	
Soldering recommendations (peak temperature) c			260	°C	

THERMAL RESISTANCE RAT	INGS				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	20	25	°C/W
Maximum junction-to-case (drain)	Steady state	R_{thJC}	1.5	1.9	C/VV

- Package limited
- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

 Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

 Maximum under steady state conditions is 63 °C/W $T_C = 25$ °C



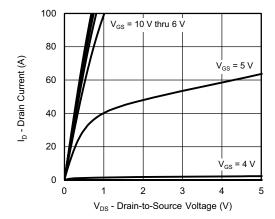
Vishay Siliconix

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			· L	L			
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	80	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	62	-	1400	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-7.3	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	-	3.8	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	100	nA	
-		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40	-	-	Α	
	, ,	V _{GS} = 10 V, I _D = 10 A	-	0.0060	0.0072		
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 7.5 V, I _D = 10 A	-	0.0070	0.0087	Ω	
Forward transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 10 A	-	50	-	S	
Dynamic ^b	313	50 , 5			<u> </u>		
Input capacitance	C _{iss}		-	1930	-		
Output capacitance	C _{oss}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	245	-	pF	
Reverse transfer capacitance	C _{rss}		- 4		-	7	
		$V_{DS} = 40 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	27.6	42		
Total gate charge	Q _g		-	21	32		
Gate-source charge	Q _{gs}	$V_{DS} = 40 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	9.3	-	nC	
Gate-drain charge	Q _{gd}		-	4.3	-		
Output charge	Q _{oss}	V _{DS} = 40 V, V _{GS} = 0 V	-	32.5	-		
Gate resistance	R_g	f = 1 MHz	0.3	0.83	1.5	Ω	
Turn-on delay time	t _{d(on)}		-	12	24		
Rise time	t _r	V_{DD} = 40 V, R_L = 4 $\Omega,I_D\cong$ 10 A,	-	6	12		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	19	38		
Fall time	t _f		-	6	12	ns	
Turn-on delay time	t _{d(on)}		-	14	28	113	
Rise time	t _r	V_{DD} = 40 V, R_L = 4 $\Omega,I_D\cong$ 10 A,	-	7	14		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$	-	18	36		
Fall time	t _f		-	7	14		
Drain-Source Body Diode Characterist	ics		_			,	
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	59.7	Α	
Pulse diode forward current	I _{SM}		-	-	150		
Body diode voltage	V _{SD}	$I_S = 5 A, V_{GS} = 0 V$	-	0.77	1.1	V	
Body diode reverse recovery time	t _{rr}		-	41	82	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	54	108	nC	
Reverse recovery fall time	t _a	T _J = 25 °C	-	28	-	ns	
Reverse recovery rise time	t _b		-	13	-	113	

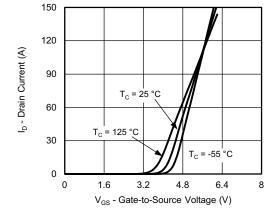
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

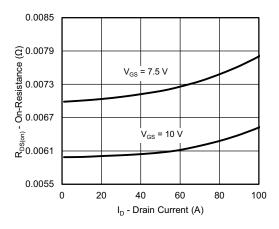




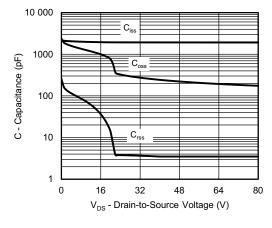
Output Characteristics



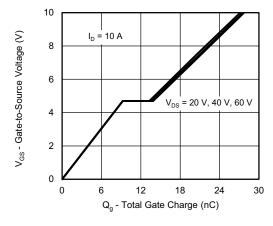
Transfer Characteristics



On-Resistance vs. Drain Current and Gate Voltage

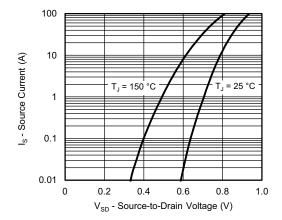


Capacitance

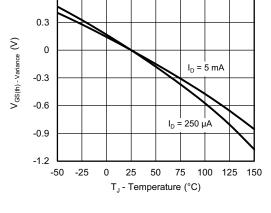


Gate Charge On-Resistance vs. Junction Temperature



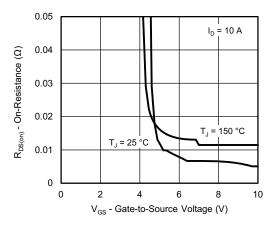


Source-Drain Diode Forward Voltage

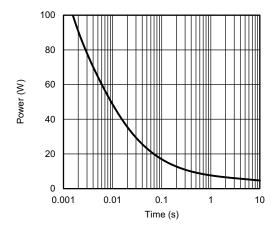


0.6

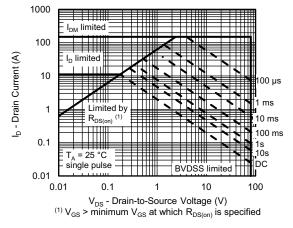
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage

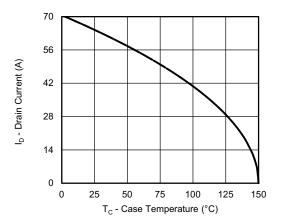


Single Pulse Power, Junction-to-Ambient

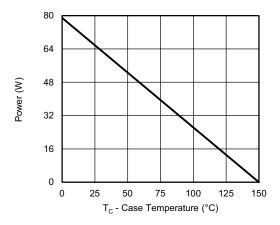


Safe Operating Area, Junction-to-Ambient

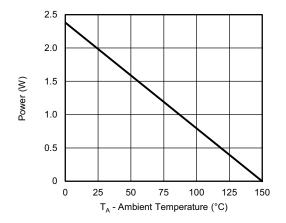




Current Derating a





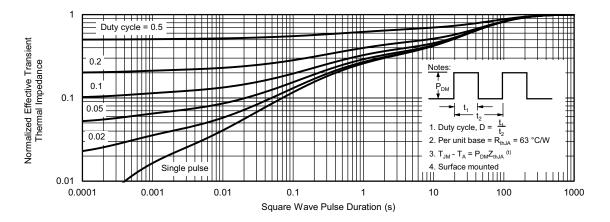


Power, Junction-to-Ambient

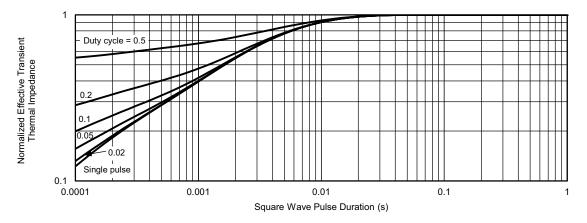
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?77833.



www.vishay.com

Case Outline for PowerPAK® 1212-8S





DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.67	0.75	0.83	0.026	0.030	0.033	
A1	0.00	-	0.05	0.000	-	0.002	
A3		0.20 ref.			0.008 ref		
b	0.25	0.30	0.35	0.010	0.012	0.014	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.15	2.25	2.35	0.085	0.089	0.093	
E	3.20	3.30	3.40	0.126	0.130	0.134	
E1	1.60	1.70	1.80	0.063	0.067	0.071	
е		0.65 bsc.			0.026 bsc.		
K		0.76 ref.			0.030 ref.		
K1	0.41 ref.			0.016 ref.			
L	0.33	0.43	0.53	0.013	0.017	0.021	
Z	0.525 ref.			0.021 ref.			

ECN: C20-0862-Rev. B, 20-Jul-2020

DWG: 6008



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